



PMEG10010ELXE-Q

100 V, 1 A low leakage current Schottky barrier rectifier

5 January 2024

Product data sheet

1. General description

Planar Schottky barrier rectifier encapsulated in a CFP3-HP (SOD123HP) power flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Extremely low leakage current
- High surge current robustness
- High power capability due to clip bond package
- Power flat lead plastic package with exposed heatsink for optimal thermal connection
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Freewheeling application
- Reverse polarity protection
- OR-ing

4. Quick reference data

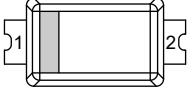

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 170$ °C	-	-	1	A
V_R	reverse voltage	$T_j = 25$ °C	-	-	100	V
V_F	forward voltage	$I_F = 1$ A; pulsed; $T_j = 25$ °C	[1]	720	780	mV
I_R	reverse current	$V_R = 100$ V; pulsed; $T_j = 25$ °C	[1]	30	150	nA
		$V_R = 100$ V; pulsed; $T_j = 125$ °C	[1]	60	500	μ A

[1] Very short pulse, in order to maintain a stable junction temperature.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 CFP3-HP (SOD123HP)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG10010ELXE-Q	CFP3-HP	Power plastic surface mounted package; 2 terminals; 2.80 mm × 1.80 mm × 0.90 mm body	SOD123HP

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG10010ELXE-Q	H2

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ °C}$		-	100	V
I_F	forward current	$\delta = 1; T_{sp} \leq 169\text{ °C}$		-	1.4	A
$I_{F(AV)}$	average forward current	$\delta = 0.5; f = 20\text{ kHz};$ square wave; $T_{sp} \leq 170\text{ °C}$		-	1	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8.3\text{ ms};$ half sine wave; $T_{j(\text{init})} = 25\text{ °C}$		-	50	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]	-	0.75	W
			[2]	-	1.3	W
T_j	junction temperature			-	175	°C
T_{amb}	ambient temperature			-55	175	°C
T_{stg}	storage temperature			-65	175	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	200	K/W
			[3] [2]	-	-	115	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	6	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.

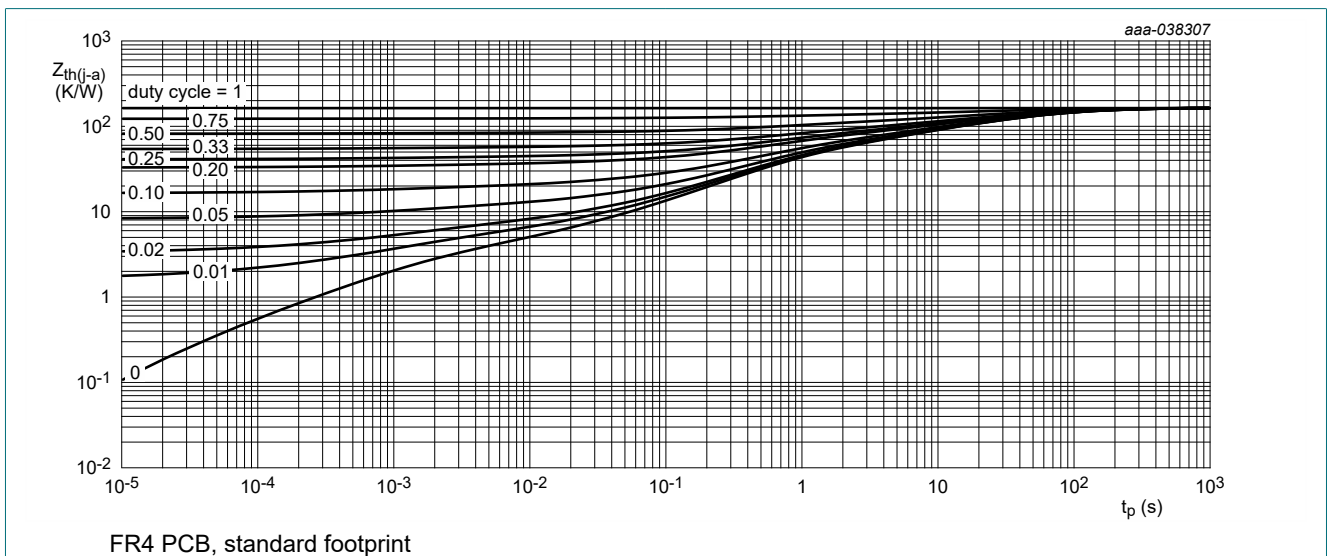


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

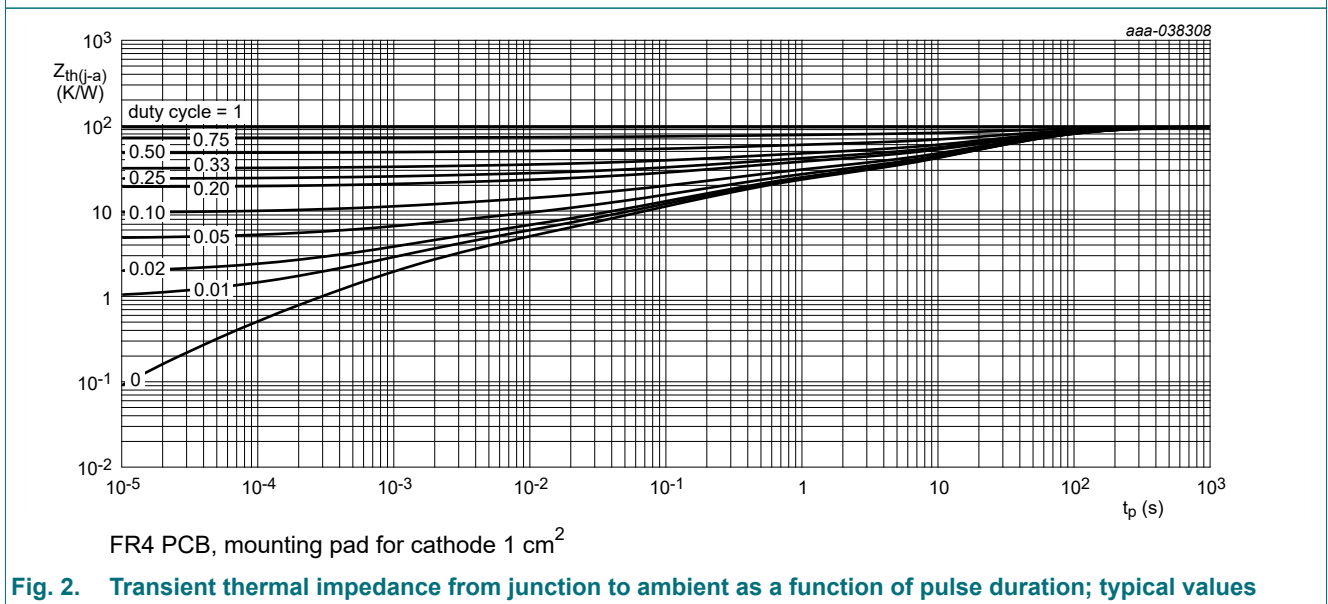


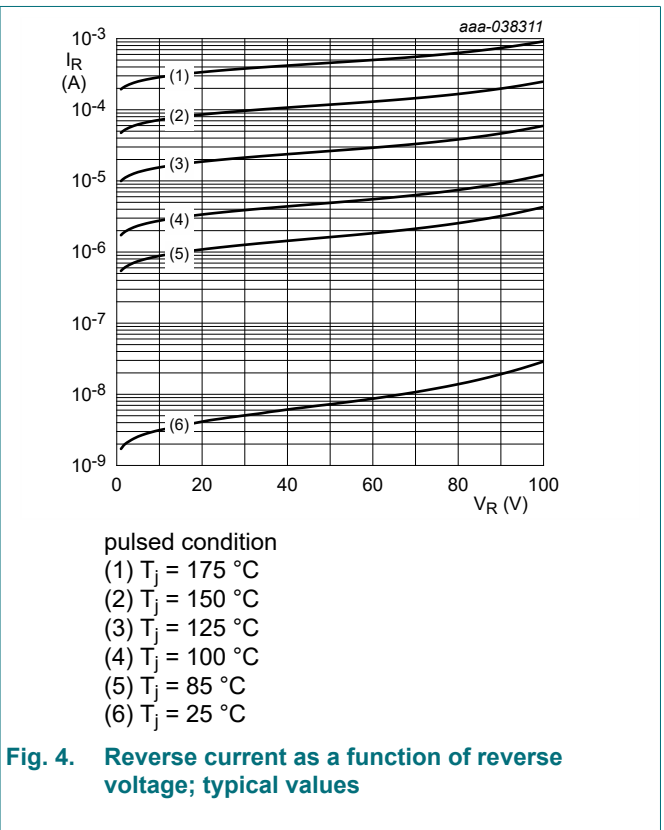
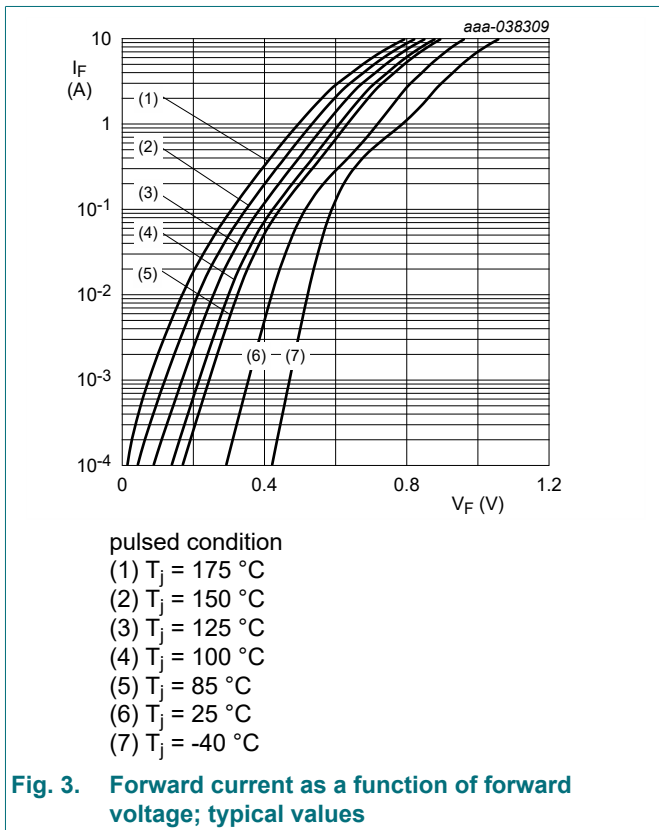
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

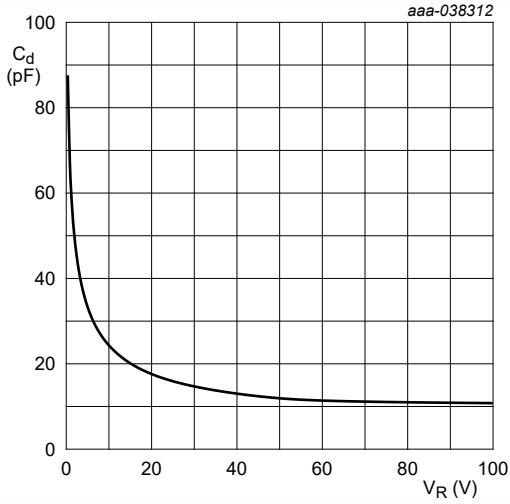
10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 1 \text{ mA}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	100	-	V	
V_F	forward voltage	$I_F = 0.5 \text{ A}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	655	725	mV
		$I_F = 1 \text{ A}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	720	780	mV
		$I_F = 1 \text{ A}$; pulsed; $T_j = -40 \text{ }^\circ\text{C}$	[1]	-	790	860	mV
		$I_F = 1 \text{ A}$; pulsed; $T_j = 125 \text{ }^\circ\text{C}$	[1]	-	575	680	mV
I_R	reverse current	$V_R = 100 \text{ V}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	30	150	nA
		$V_R = 100 \text{ V}$; pulsed; $T_j = 125 \text{ }^\circ\text{C}$	[1]	-	60	500	μA
C_d	diode capacitance	$V_R = 1 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$		-	55	-	pF
		$V_R = 10 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$		-	25	-	pF
t_{rr}	reverse recovery time ; step recovery	$I_F = 0.5 \text{ A}$; $I_R = 0.5 \text{ A}$; $I_{R(\text{meas})} = 0.1 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$		-	4	-	ns
	reverse recovery time ; ramp recovery	$dI_F/dt = 200 \text{ A}/\mu\text{s}$; $I_F = 6 \text{ A}$; $V_R = 26 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$		-	14	-	ns
I_{RM}	peak reverse recovery current			-	1.6	A	
Q_{rr}	reverse recovery charge			-	13	nC	
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}$; $dI_F/dt = 20 \text{ A}/\mu\text{s}$; $T_j = 25 \text{ }^\circ\text{C}$		-	680	mV	

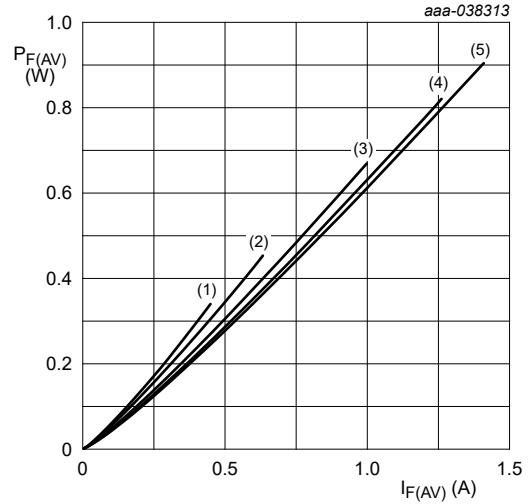
[1] Very short pulse, in order to maintain a stable junction temperature.





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

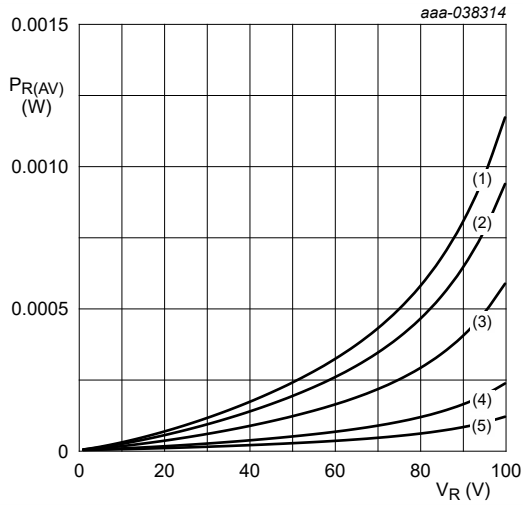
Fig. 5. Diode capacitance as a function of reverse voltage; typical values



$T_j = 100 \text{ }^\circ\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 0.8$
- (5) $\delta = 1$

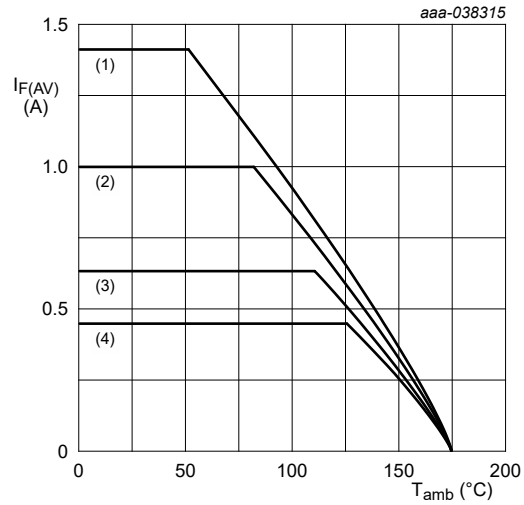
Fig. 6. Average forward power dissipation as a function of average forward current; typical values



$T_j = 100 \text{ }^\circ\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.8$
- (3) $\delta = 0.5$
- (4) $\delta = 0.2$
- (5) $\delta = 0.1$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values

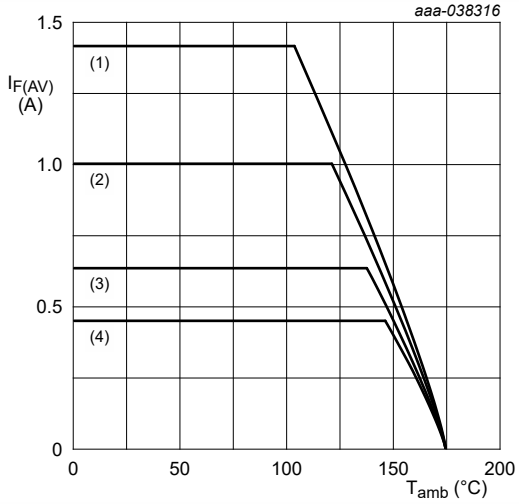


FR4 PCB, standard footprint

$T_j = 175 \text{ }^\circ\text{C}$

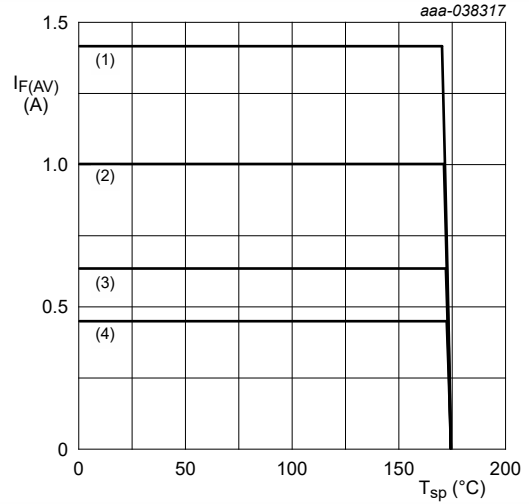
- (1) $\delta = 1$
- (2) $\delta = 0.5; f = 20 \text{ kHz}$
- (3) $\delta = 0.2; f = 20 \text{ kHz}$
- (4) $\delta = 0.1; f = 20 \text{ kHz}$

Fig. 8. Average forward current as a function of ambient temperature; typical values



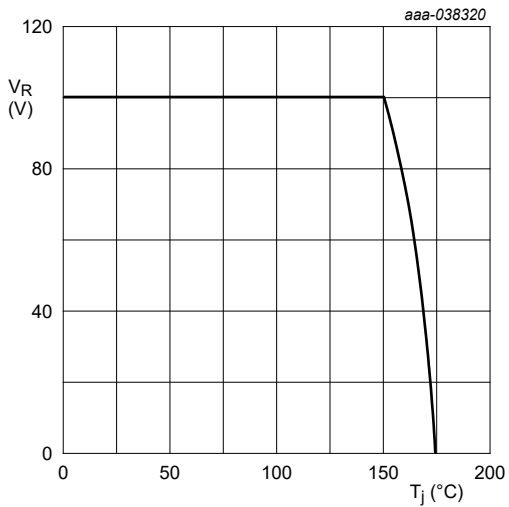
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 175$ °C
 (1) $\delta = 1$
 (2) $\delta = 0.5$; $f = 20$ kHz
 (3) $\delta = 0.2$; $f = 20$ kHz
 (4) $\delta = 0.1$; $f = 20$ kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



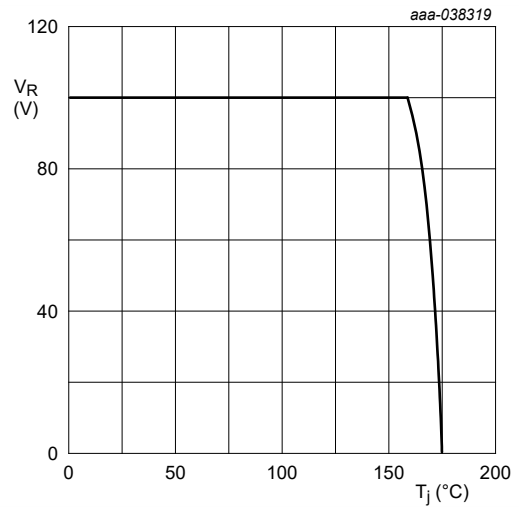
$T_j = 175$ °C
 (1) $\delta = 1$
 (2) $\delta = 0.5$; $f = 20$ kHz
 (3) $\delta = 0.2$; $f = 20$ kHz
 (4) $\delta = 0.1$; $f = 20$ kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values



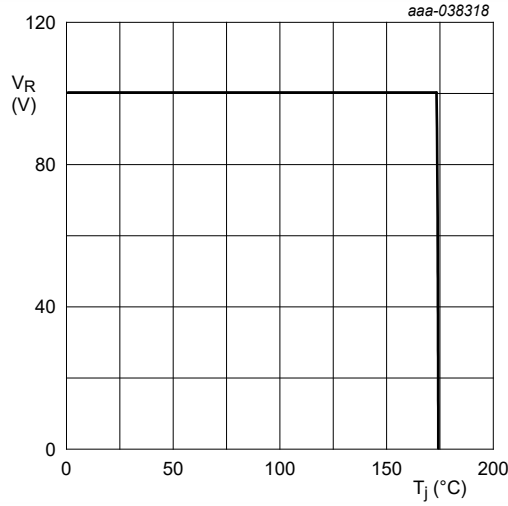
FR4 PCB, standard footprint
 $R_{th} = 200$ K/W

Fig. 11. Derated maximum reverse voltage as a function of junction temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²
 $R_{th} = 115$ K/W

Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



Soldering point of cathode tab
 $R_{th} = 6 \text{ K/W}$

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

11. Test information

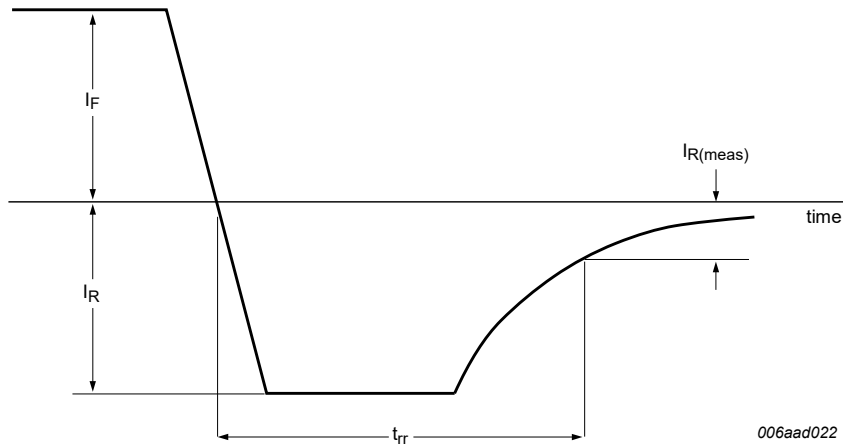


Fig. 14. Reverse recovery definition; step recovery

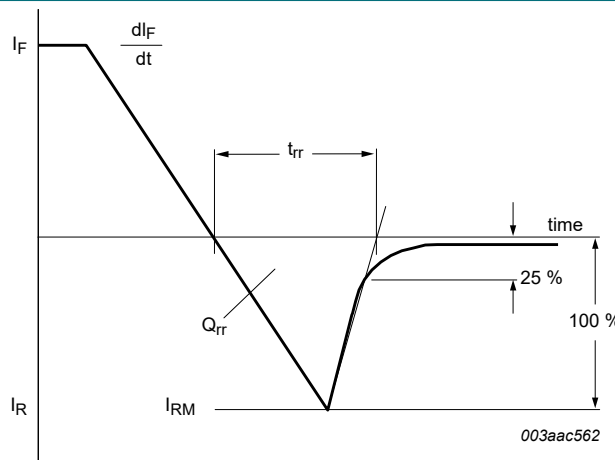


Fig. 15. Reverse recovery definition; ramp recovery

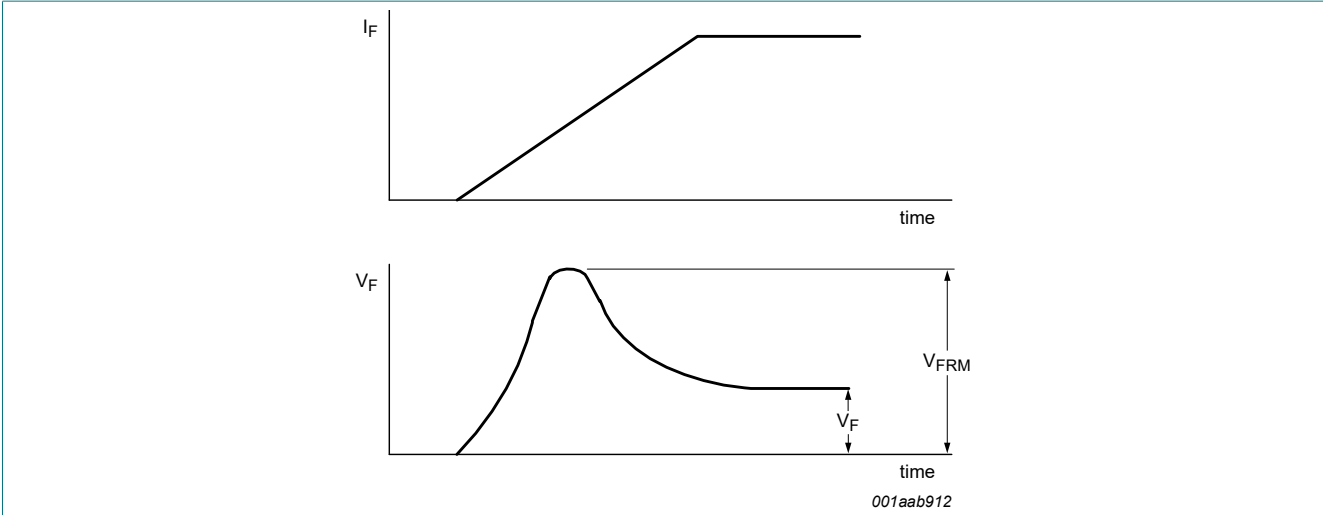


Fig. 16. Forward recovery definition

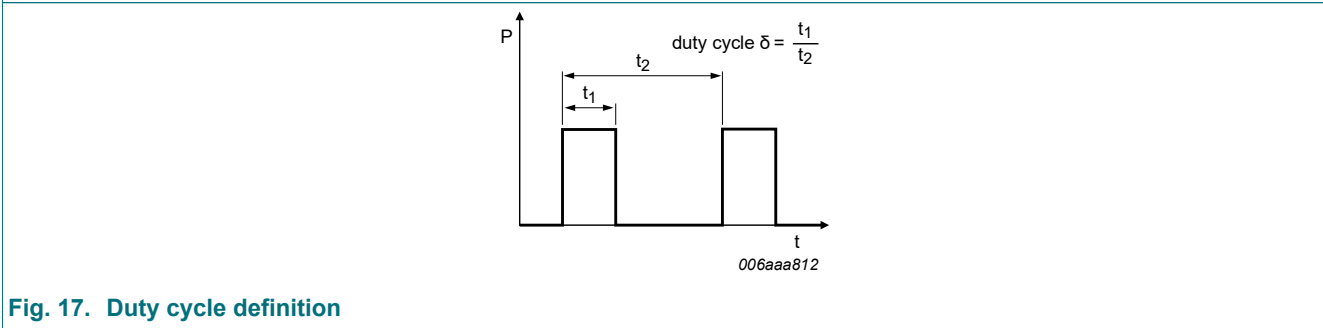


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC, and } I_{RMS} = I_M \times \sqrt{\delta}$$

with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

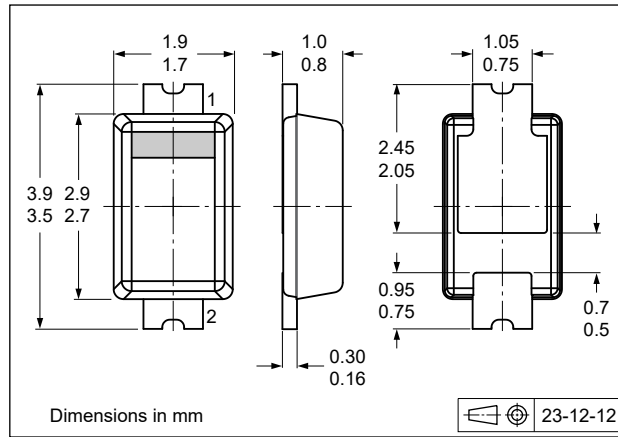


Fig. 18. Package outline CFP3-HP (SOD123HP)

13. Soldering

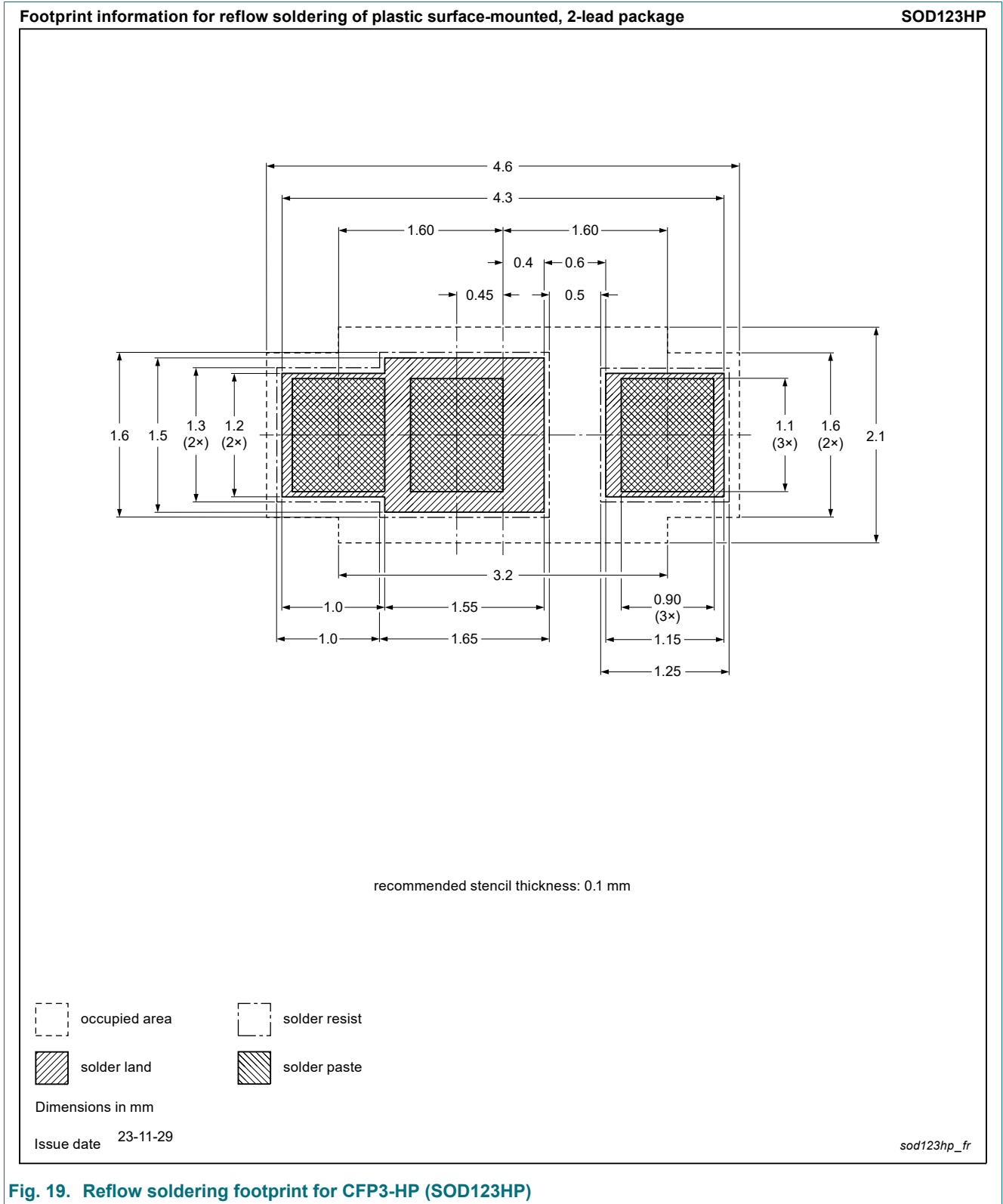


Fig. 19. Reflow soldering footprint for CFP3-HP (SOD123HP)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG10010ELXE-Q v.1	20240105	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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